

U.S.S.N. 10/804,899

Claim Amendments

Please amend claim 1 as follows:

Please add new claims 21- 30 as follows:

Claims as Amended

1. A capacitor comprising:

a substrate;

a first capacitor plate layer formed disposod over the
substrate, the first capacitor plate layer comprising a
horizontally separated and contiguously interconnected first
series of tines disposed on a dielectric layer;

a second capacitor plate layer separated from the first
capacitor plate layer by a contiguous serpentine shaped
capacitor dielectric layer, the second capacitor plate layer

U.S.S.N. 10/804,899

comprising a horizontally separated and contiguously interconnected second series of tines, said second series of tines horizontally interdigitated between the horizontally separated and interconnected first series of tines, wherein the capacitor dielectric layer is a single serpentine conformal dielectric layer.

2. (original) The capacitor of claim 1 wherein the second series of tines is horizontally interdigitated but not vertically interdigitated with respect to the first series of tines.

3. (original) The capacitor of claim 1 wherein the substrate is a semiconductor substrate.

4. (original) The capacitor of claim 1 wherein the substrate is a ceramic substrate.

U.S.S.N. 10/804,899

5. (original) The capacitor of claim 1 wherein the capacitor dielectric layer is formed to a thickness of from about 20 to about 200 angstroms.

6. (original) The capacitor of claim 1 wherein the second capacitor plate also covers a series of top surfaces of the first series of tines.

Claims 7-20 cancelled

21. (new) The capacitor of claim 1 wherein the second series of tines is self-aligned with respect to the first series of tines.

22. (new) The capacitor of claim 1 wherein where the first series of tines is contiguously interconnected according to a base portion of said first series of tines, said base portion and said first series tines comprising a comb shape structure extending parallel to the horizontal plane of the substrate.

U.S.S.N. 10/804,899

23. (new) The capacitor of claim 1 wherein the second series of tines is contiguously interconnected according to a base portion of said second series of tines, said base portion and said second series tines comprising a comb shape structure extending parallel to the horizontal plane of the substrate.

24. (new) The capacitor of claim 24 wherein the second series of tines is further contiguously interconnected according to an upper conductive portion disposed over the top surface of said first series of tines.

25. (new) The capacitor of claim 1 wherein the first series of tines is encapsulated on bottom and sidewall portions.

26. (new) The capacitor of claim 1 wherein the first series of tines is encapsulated by a barrier layer on bottom and sidewall portions.

U.S.S.N. 10/804,899

27. (new) The capacitor of claim 1 wherein the second series of tines is encapsulated by a contiguous barrier layer on bottom and sidewall portions.

28. (new) The capacitor of claim 26 wherein the second series of tines including the upper conductive portion is encapsulated by a contiguous barrier layer on bottom and sidewall portions.

29. (new) A capacitor comprising:

a substrate with an overlying dielectric layer;
a comb shaped first capacitor plate disposed on the dielectric layer, said first capacitor plate layer comprising a first series of tines extending parallel to the substrate and contiguously interconnected at a base portion; and,

a comb shaped second capacitor plate layer separated from the first capacitor plate layer by a contiguous serpentine shaped capacitor dielectric layer, said second capacitor plate

U.S.S.N. 10/804,899

layer comprising a second series of tines extending parallel to the substrate and contiguously interconnected at a base portion, said second series of tines horizontally interdigitated between the first series of lines.

30. (new) A capacitor comprising:

a substrate with an overlying dielectric layer;

a comb shaped first capacitor plate disposed on the dielectric layer, said first capacitor plate layer comprising a first series of tines extending parallel to the substrate and contiguously interconnected at a base portion;

a comb shaped second capacitor plate layer separated from the first capacitor plate layer by a contiguous serpentine shaped capacitor dielectric layer, said second capacitor plate layer comprising a second series of tines extending parallel to the substrate and contiguously interconnected at a base portion,

U.S.S.N. 10/804,899

said second series of tines horizontally interdigitated between the first series of tines; and,

wherein the second series of tines is further contiguously interconnected over a top surface of said second series of tines.